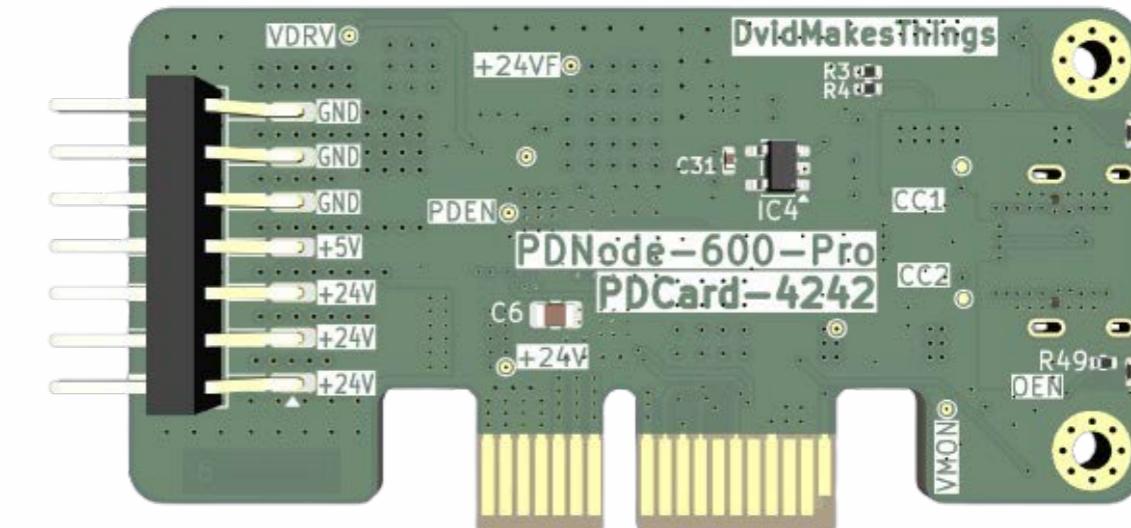


Top Preview



Bottom Preview



PDNode-600

Date:
File Name:
Sheet Title:

Project Name:
PDCard-4242
Revision:
Variant:
Pro
Company:
Designer:
David Sipos
Reviewer:
Size:
A3
Sheet:
1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

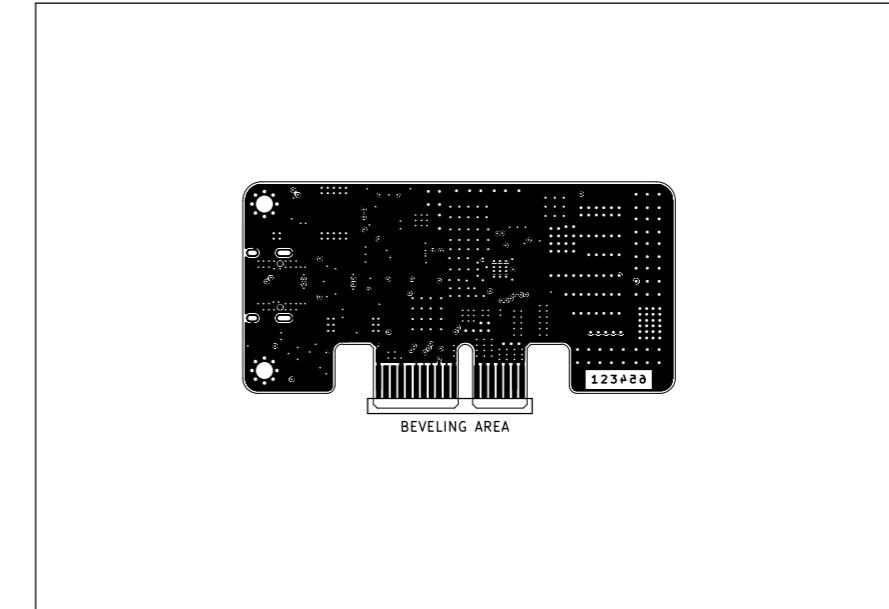
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

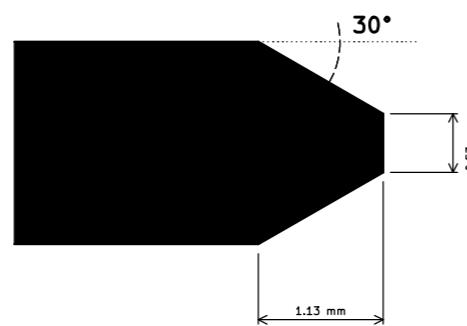
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-

1	Top Layer
2	2nd Layer
3	3rd Layer
4	4th Layer
5	5th Layer
6	Bottom Layer
7	
8	
9	
10	

PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
File Name: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: Sheet: A3 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

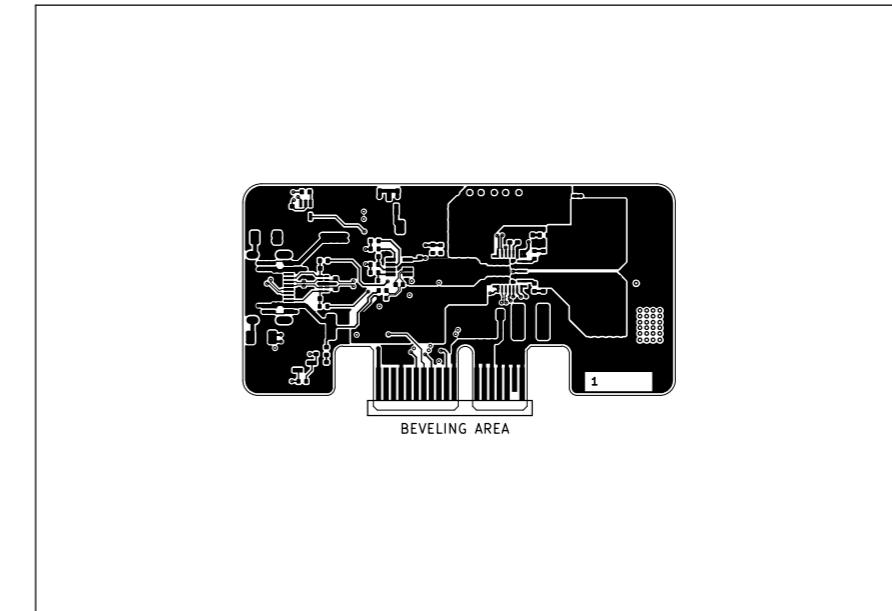
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

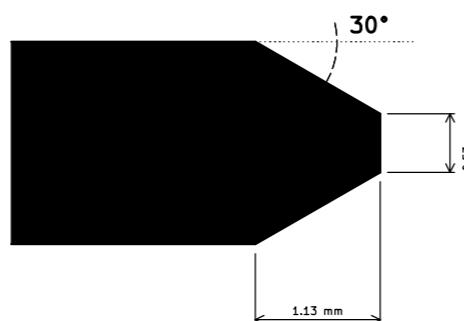
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-

1	Top Layer
2	
3	
4	
5	
6	
7	
8	
9	
10	

PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)

	Board Name:	PDCard-4242	
	File Name:	PDCard-4242.kicad_pcb	
	Sheet Title:	Company:	Designer: David Sipos
		Reviewer:	Size: A3
Sheet: 1 of 1			

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

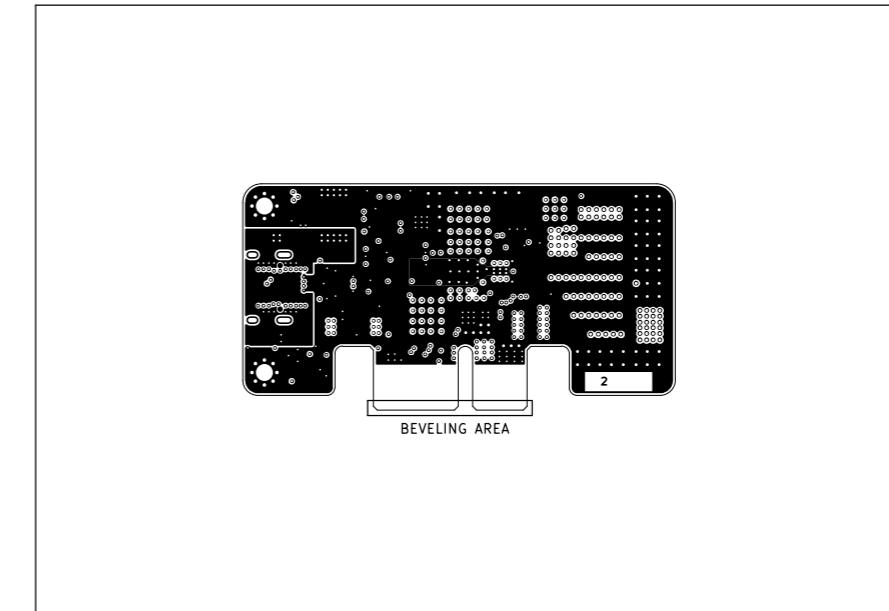
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

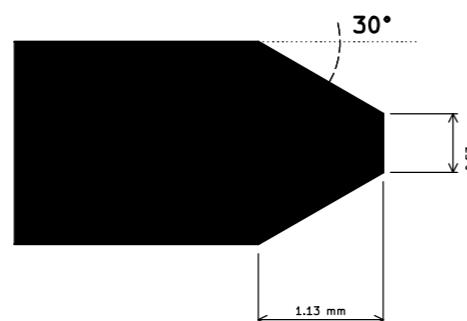
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-

1	
2	2nd Layer
3	
4	
5	
6	
7	
8	
9	
10	

PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
Date: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: Sheet: A3 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

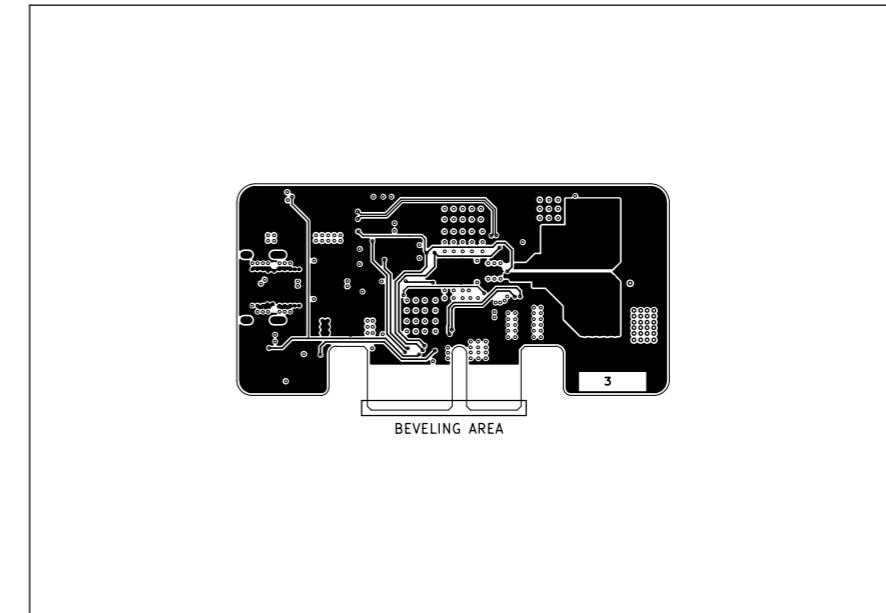
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

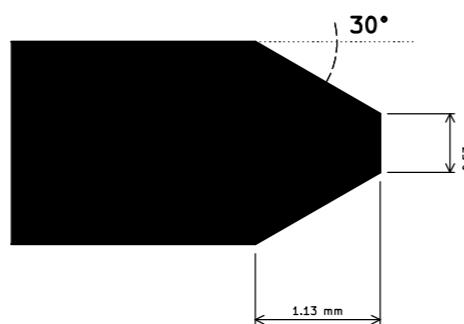
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-

1	
2	
3	3rd Layer
4	
5	
6	
7	
8	
9	
10	

PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)

	Board Name:	PDCard-4242	
	Project Name:	PDCard-4242	
	File Name:	PDCard-4242.kicad_pcb	
	Date:	Revision:	Variant:
Sheet Title:	Company:	Designer: David Sipos Reviewer:	
	Size:	Sheet:	
	A3	1 of 1	

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

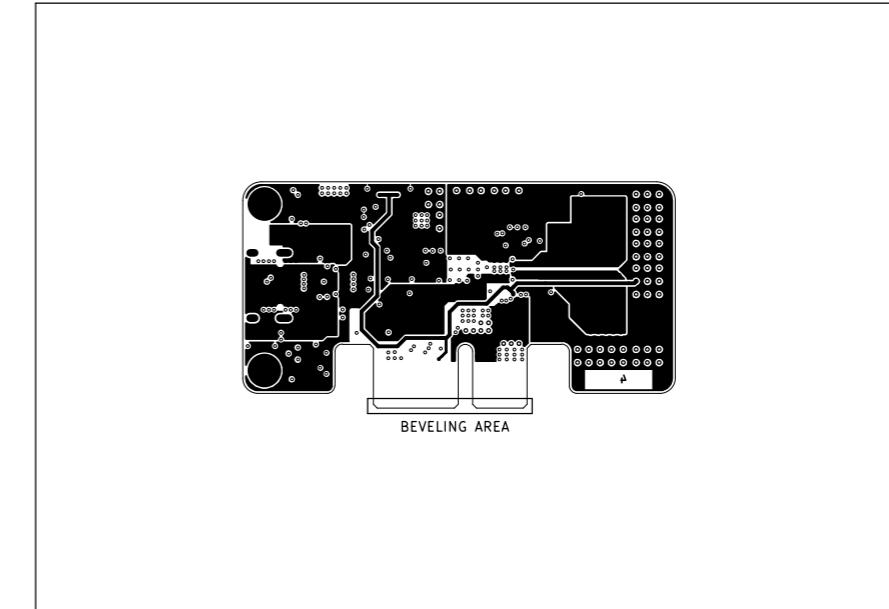
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

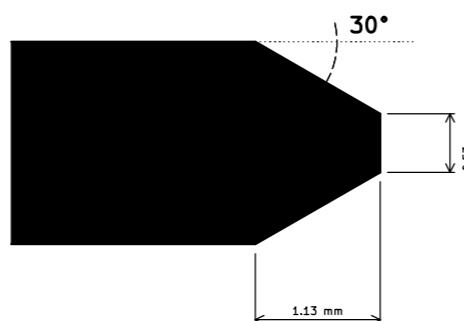
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-



PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
Date: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: Sheet: A3 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

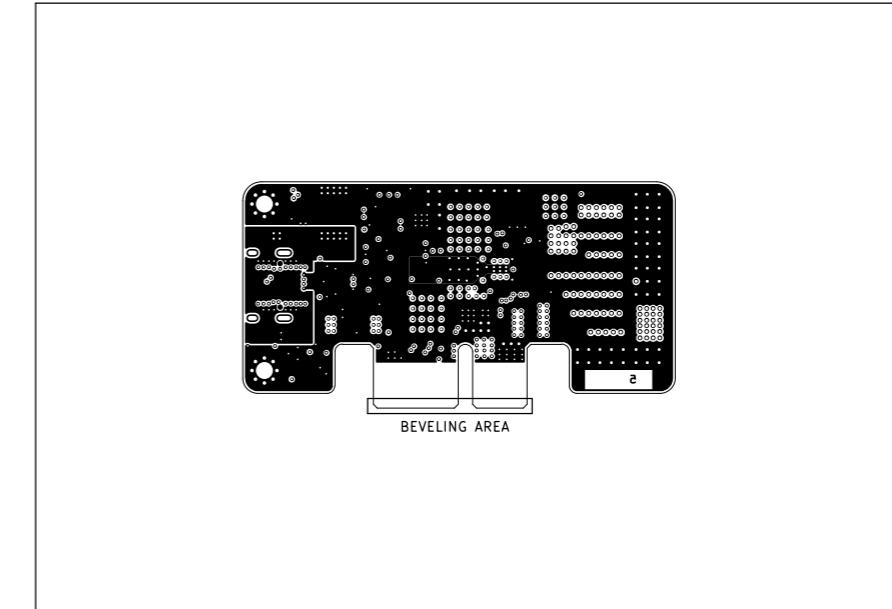
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

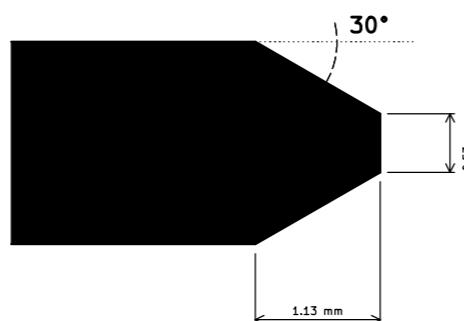
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-



PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
Date: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: A3 Sheet: 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

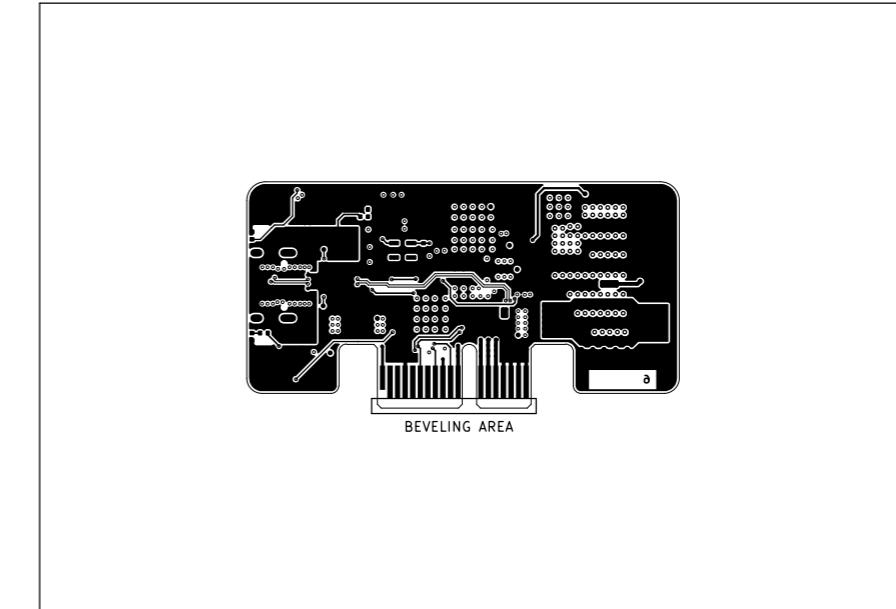
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

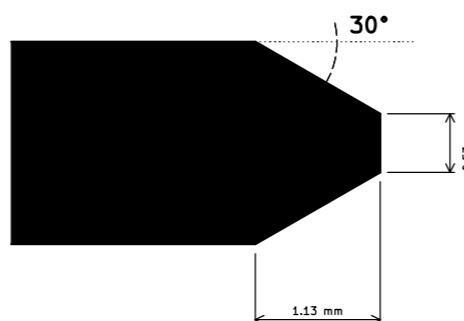
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
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Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-



PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

- * 0.200mm / 0.0079" (211 holes)
- 0.250mm / 0.0098" (124 holes)
- + 0.300mm / 0.0118" (157 holes)
- 0.400mm / 0.0157" (16 holes)
- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)

	Board Name:	PDCard-4242	
	Project Name:	PDCard-4242	
	File Name:	PDCard-4242.kicad_pcb	
	Date:	Revision:	Variant:
Sheet Title:	Company:	Designer: David Sipos Reviewer:	
Size:	A3	Sheet:	
1 of 1			

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

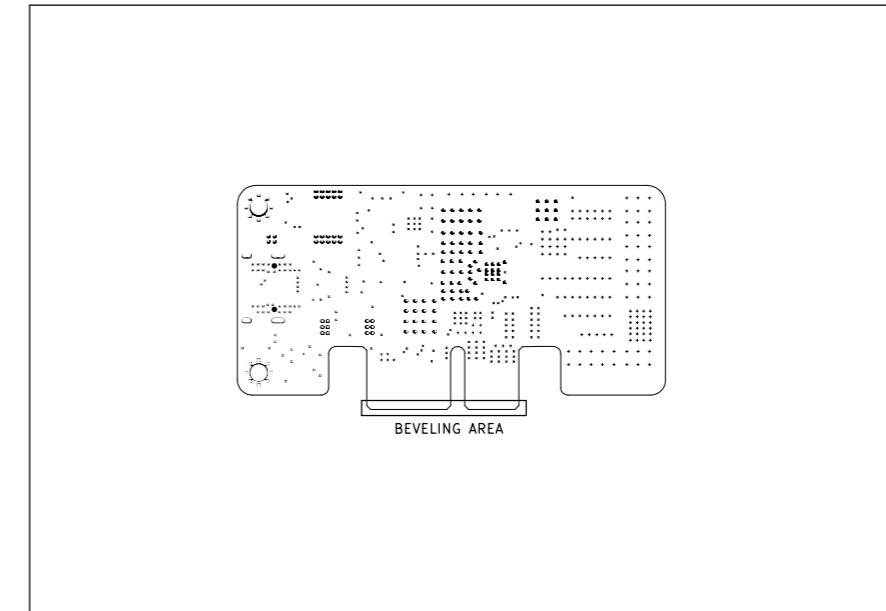
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

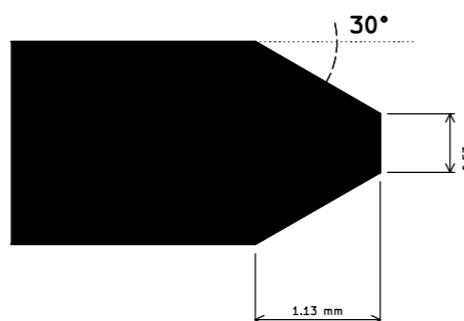
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
Dielectric 2	Core	0.55mm H/H without copper	0.55	4.41	0.02
In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
Dielectric 4	Core	0.55mm H/H without copper	0.55	4.41	0.02
In4.Cu	Copper	-	0.0152	-	-
Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-

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7	PTH Drill
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PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

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- ☒ 2.200mm / 0.0866" (2 holes)

NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
Date: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: Sheet: A3 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

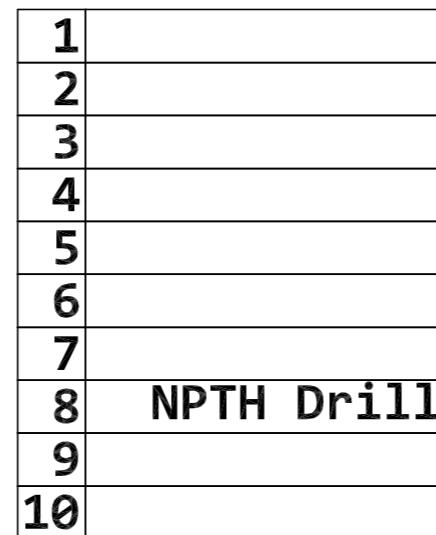
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

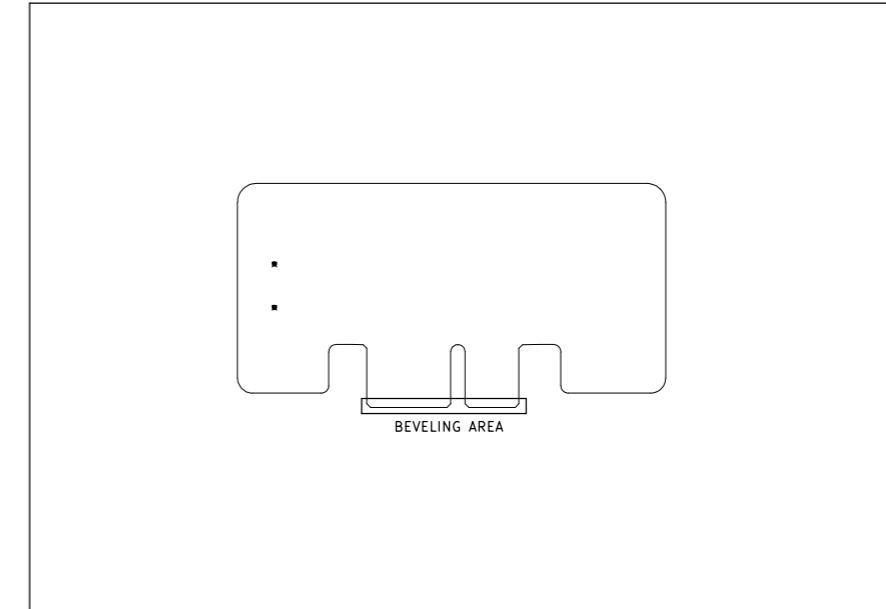
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

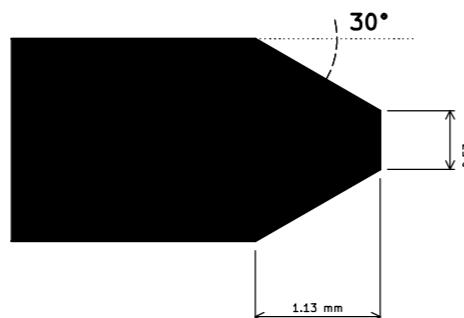
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
F.Cu	Copper	-	0.035	-	-
Dielectric 1	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
In1.Cu	Copper	-	0.0152	-	-
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In2.Cu	Copper	-	0.0152	-	-
Dielectric 3	Prepreg	2116 RC54% 4.9mil	0.1888	4.16	0.02
In3.Cu	Copper	-	0.0152	-	-
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Dielectric 5	Prepreg	3313 RC57% 4.2mil	0.0994	4.1	0.02
B.Cu	Copper	-	0.035	-	-
B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-



PCB AREA



BEVELING



PTH DRILLMAP

Drill Map:

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- ◊ 0.600mm / 0.0236" (0 holes + 4 slots)
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NPTH DRILLMAP

Drill Map:

- ✗ 0.650mm / 0.0256" (2 holes) (not plated)



Board Name: PDNode-600	Project Name: PDCard-4242
Date: PDNode-PDCard-4242.kicad_pcb	Revision: Variant: Pro
Sheet Title: Company: Designer: Reviewer:	Size: Sheet: A3 1 of 1

PDCard-4242 Schematic Documentation

PDNode-600 Baseboard

PCB FABRICATION SPECIFICATION

BOARD PARAMETERS

Layers: 6
 Board Size: 57.17 mm x 29.92 mm
 PCB Thickness: 1.6 mm
 Base Material: FR-4
 Material Type: FR4 TG135
 Stackup Code: JLC06161H-3313
 Impedance Control: No requirement
 Appearance Standard: IPC Class 2
 Board Outline Tolerance: ±0.2 mm

COPPER & FINISH

Outer Copper Weight: 1 oz
 Inner Copper Weight: 0.5 oz
 Surface Finish: ENIG
 Gold Thickness: 1 U"
 Gold Fingers: YES
 Beveling: Yes, 30°

SOLDER MASK & SILK

PCB Color: Green
 Silkscreen Color: White
 Via Covering: Epoxy Filled & Capped

DRILLING & SPECIAL PROCESSES

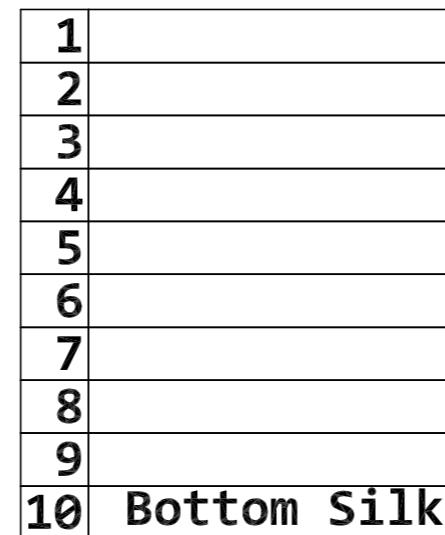
Min Via Hole: 0.2 mm
 Via Pad / Finished Diameter: 0.4 mm
 Castellated Holes: No
 Edge Plating: No
 Blind Slot: No
 Press-Fit Hole: No
 Countersink Hole: No
 Backdrill: No

QUALITY & TEST

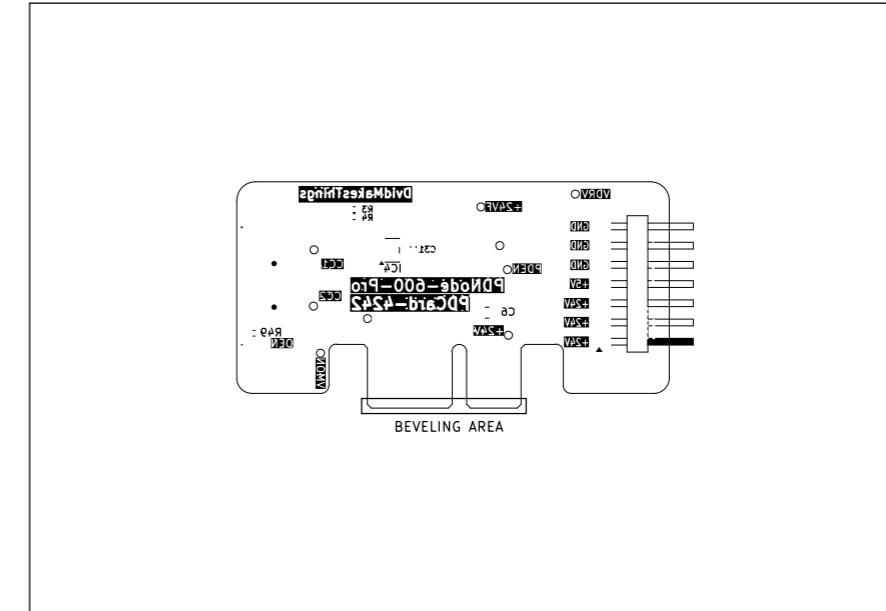
Electrical Test: Flying Probe Fully Test

LAYER STACKUP

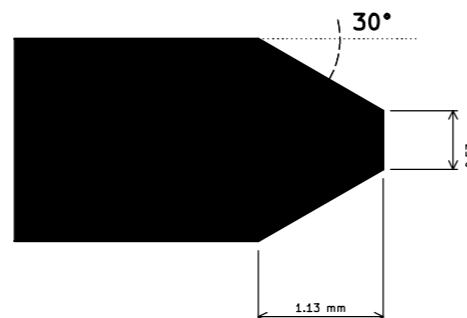
Name	Type	Material	Thickness mm	Er	LossTg
F.Silkscreen	Top Silk	Direct Printing White	-	-	-
F.Paste	Paste	-	-	-	-
F.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
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B.Mask	Solder Mask	Solder Resist Green	0.01	3.8	0
B.Paste	Paste	-	-	-	-
B.Silkscreen	Bottom Silk	Direct Printing White	-	-	-



PCB AREA



BEVELING



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Board Name: PDNode-600	Project Name: PDCard-4242
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Sheet Title: Company:	Designer: David Sipos
Sheet Title: Company:	Reviewer: A3
Sheet Title: Company:	Size: A3
Sheet Title: Company:	Sheet: 1 of 1